



# Wright State University

EE480/680

## Micro-Electro-Mechanical Systems (MEMS)

Summer 2006



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## Transducers: Actuators

## Overview

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- Transducers
- Basic Mechanics
- Actuators
  - Electrostatic
  - Electro-Thermal
  - Bimorph Electro-Thermal
  - Residual Stress
  - Mechanical Components

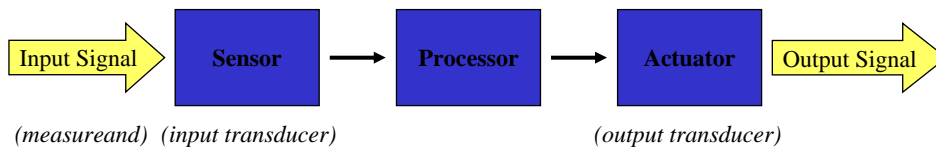
## Transducers

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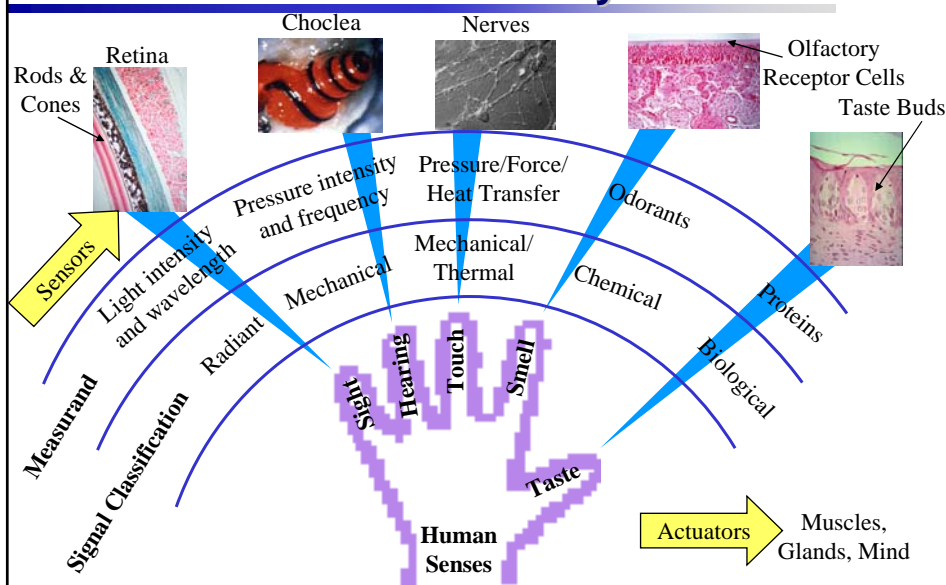
- Transducer: a device that transfers power from one form to another
- Transducers can be divided into two categories
  - Sensors – reacts to environment
  - Actuators – acts on environment
- Can you think of common examples of sensors and actuators?

# Transducers

- Transducer Schemes
  - One or more of the below components may or may not be utilized
  - A transducer can perform a dual role as sensor and actuator



## Transducers: Examples from the Human Body



# Transducers

- Sensor Classification

After Gardner, *Microsensors*, 1994.

Signal Classification	Measurands
Thermal	Temperature, heat, heat flow, entropy, heat capacity, and etc.
Radiation	Gamma rays, X-rays, ultra-violet, visible, infra-red, micro-waves, radio waves, phase, and etc.
Mechanical	Position, displacement, velocity, acceleration, force, torque, pressure, mass, flow, acoustic wavelength and amplitude, and etc.
Magnetic	Magnetic field, flux, magnetic moment, magnetization, magnetic permeability, and etc.
Chemical	Humidity, pH level and ions, concentration of gases, vapors and odors, toxic and flammable materials, pollutants, and etc.
Biological	Sugars, proteins, hormones, antigens, and etc.
Electrical	Charge, current, voltage, resistance, conductance, capacitance, inductance, dielectric permittivity, phase, frequency, and etc.

# Transducers

- Actuator Classification

Signal Classification	Action
Thermal	heat, cool, radiate, and etc.
Radiation	emit light and other radiation
Mechanical	Provide displacement, velocity, acceleration, force, torque, pressure, mass, flow, and etc.
Magnetic	Provide magnetic field, flux, magnetic moment, magnetization, magnetic permeability, etc.
Chemical	Change/Provide humidity, pH level and ions, concentration of gases, vapors and odors, muscle stimulation, and etc.
Biological	Provide mechanical actuation, computing, etc.
Electrical	Provide charge, current, voltage, and etc.

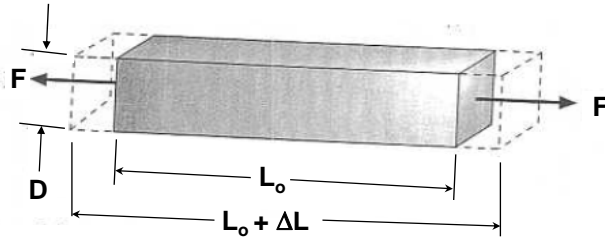
# Transducers

- Ideal Sensor Characteristics
  - Linear Operation
  - Noise Free Response
  - Zero Baseline
  - Fast Response Time
  - Large Frequency Bandwidth
  - No Saturation
  - High Sensitivity
  - High Resolution
  - Reliable and Rugged
  - No Performance Drift
  - Intolerant to Interference
  - No Hysteresis, Repeatable
  - Low Power Consumption
  - Simple Construction
- Ideal Actuator Characteristics
  - Aforementioned, plus ....
  - High Force Per Unit Volume
  - Large Deflections
  - Simplicity of Drive and Control
  - Simple Interface

# Overview

- Transducers
- Basic Mechanics
- Actuators
  - Electrostatic
  - Electro-Thermal
  - Bimorph Electro-Thermal
  - Residual Stress
  - Mechanical Components

## Axial Stress & Strain

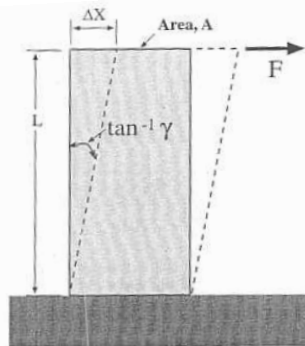


- Strain,  $\epsilon$ , is the deformation of a solid ( $\Delta L/L$ ) due to stress
- Stress,  $\sigma$ , is the force acting on a unit area of a solid ( $F/A$ )
- The Young's Modulus,  $E$ , is the ratio of stress over strain
  - describes the "firmness" of a material (hard,  $E$  Large, soft,  $E$  small)

$$E = \frac{\text{stress}}{\text{strain}} = \frac{\sigma}{\epsilon} \quad (\text{typically in N/m}^2)$$

Micromachined Transducers Sourcebook G. Kovacs ©1997

## Shear Stress & Strain



- Shear stress is force applied to an object in the plane of an opposing force
  - Such as an anchor point
- The shear modulus of elasticity,  $G$ , represents the degree of displacement an object will allow under shear stress.
- Shear strain,  $\gamma$ , is related to the angle that a deformed element's sides make with respect to its original shape

$$G = \frac{\text{shear stress}}{\text{shear displacement angle (rad)}} = \frac{\tau}{\gamma} = \frac{\frac{F}{A}}{\frac{\Delta X}{L}} \quad (\text{typically in N/m}^2)$$

Micromachined Transducers Sourcebook G. Kovacs ©1997

## Shear Stress & Strain Cont.

For isotropic materials (those having identical properties in every direction, generally not the case for most single-crystal materials, Shear modulus,  $G$ , is related to the elastic modulus,  $E$ , by

$$E = 2G(1 + \mu) = 3K(1 - 2\mu) \quad \begin{array}{l} \mu \text{ is Poisson's ratio} \\ K \text{ is the bulk modulus} \end{array}$$

The bulk modulus is defined as the ratio of hydrostatic stress to volume compression

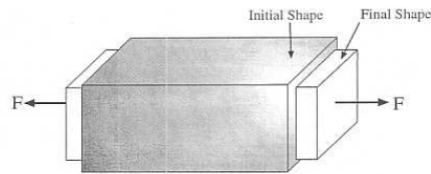
$$K = \frac{\text{hydrostatic stress}}{\text{volume compression}} = \frac{\frac{F}{A}}{\frac{\Delta V}{V}} \quad \text{in N/m}^2$$

The bulk modulus of a material represents its volume change under uniform pressure. In general, solids are less compressible than liquids due to their rigid atomic lattices

For Ex. Water –  $K = 2.0 \times 10^9 \text{ N/m}^2$   
 Aluminum –  $K = 7 \times 10^{10} \text{ N/m}^2$   
 Steel –  $K = 14 \times 10^{10} \text{ N/m}^2$

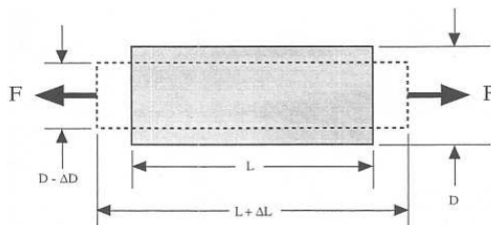
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## Poisson's Strain



$$\epsilon_a = \frac{\Delta L}{L_o} \quad \text{axial strain}$$

$$\epsilon_t = \frac{\Delta D}{D_o} \quad \text{transverse strain}$$



$$\mu = \frac{\text{transverse strain}}{\text{longitudinal strain}} = -\frac{\epsilon_t}{\epsilon_a} = -\frac{\frac{\Delta D}{D_o}}{\frac{\Delta L}{L_o}}$$

Poisson's ratio  $\nu$  or  $\mu$  always defined as a positive value

Typical values are 0.2 to 0.5 for most materials  
 For most metals, Poisson's ratio is ~ 0.3  
 Rubber's have a Poisson's ratio closer to 0.5  
 Cork has a Poisson's ratio close to 0

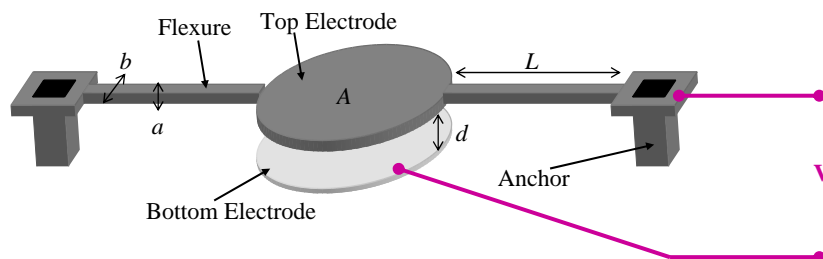
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## Actuators: Electrostatic

- Advantages
  - Simple Designs
  - Simple Fabrication
  - High Frequency Operation
  - Low Power
- Disadvantages
  - Low Force Per Unit Volume
  - High Drive Voltages
  - Nonlinear Operation

## Actuators: Electrostatic

- Parallel Plate
  - Two plate like structures facing each other, with a potential difference between them, will be drawn together due to the force of electrostatic attraction.





# Actuators: Electrostatic

- Parallel Plate Examples

Vertical Switch

Piston Mirror  
W. D. Cowan, AFIT

200  $\mu\text{m}$

100  $\mu\text{m}$

N.O. N.O. N.C.

Attraction Plate

Contact Plates

Solder Joint

N.C.

N.O.

Attraction Plate

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17

# Actuators: Electrostatic

- Parallel Plate Examples: Texas Instruments Digital Micromirror Device™

16  $\mu\text{m}$

Mirror

Mirror Support Post

Landing Tips

Torsion Hinge

Address Electrode

Yoke

Electrode Support Post

Hinge Support Post

Metal 3 Address Pads

Landing Sites

Bias/Reset Bus

To SRAM

SXGA device with black aperture: 1280x1024; 1,310,720 mirrors

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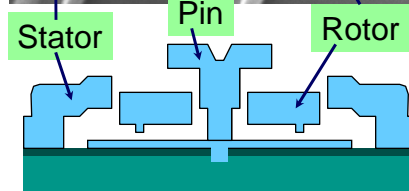
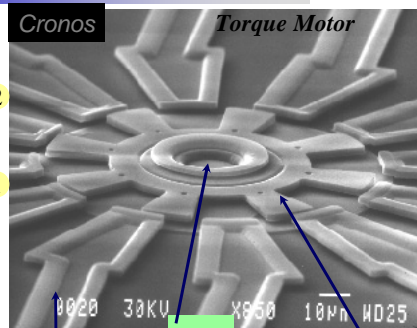
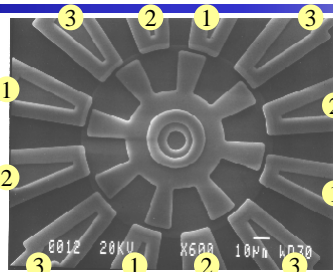
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## Actuators: Electrostatic

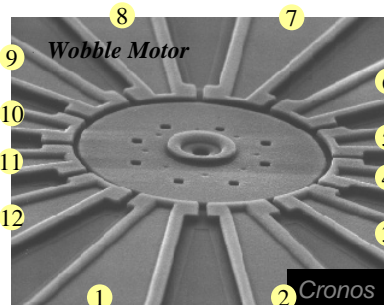
- Notes:
  - Displacement vs. Actuation Voltage
  - Spring Constants
  - Damping Coefficient
  - Lumped Element Dynamic Model

## Actuators: Electrostatic

- Rotary

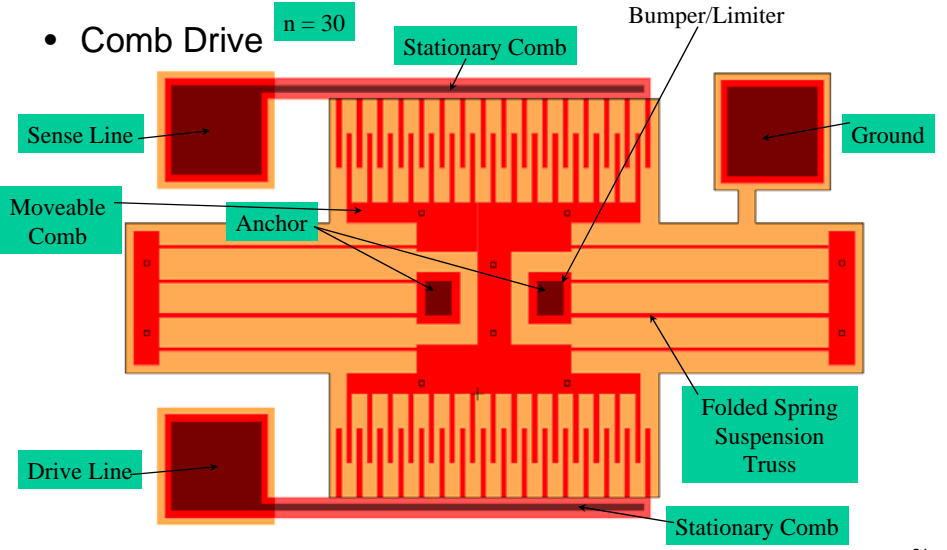


Cross section of motor



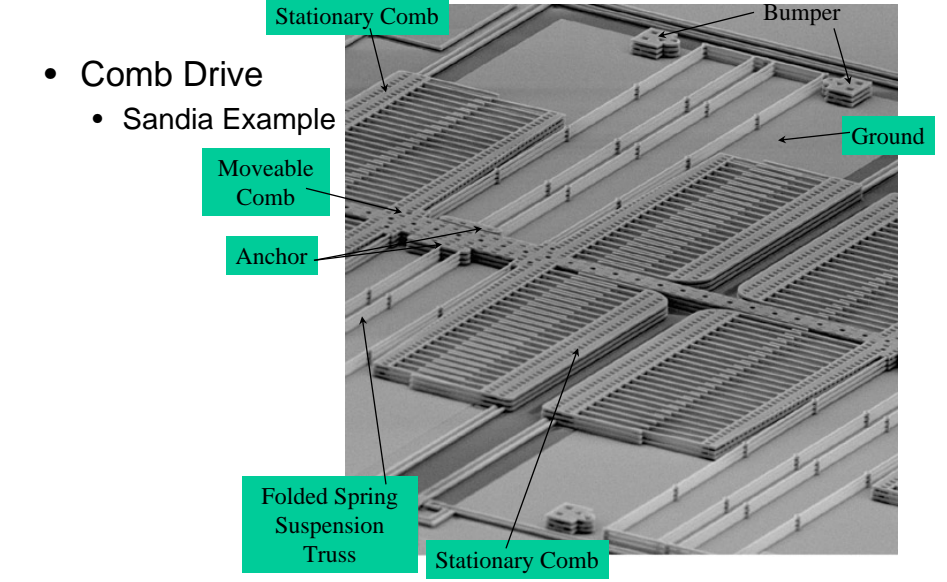
# Actuators: Electrostatic

- Comb Drive  $n = 30$



# Actuators: Electrostatic

- Comb Drive
  - Sandia Example

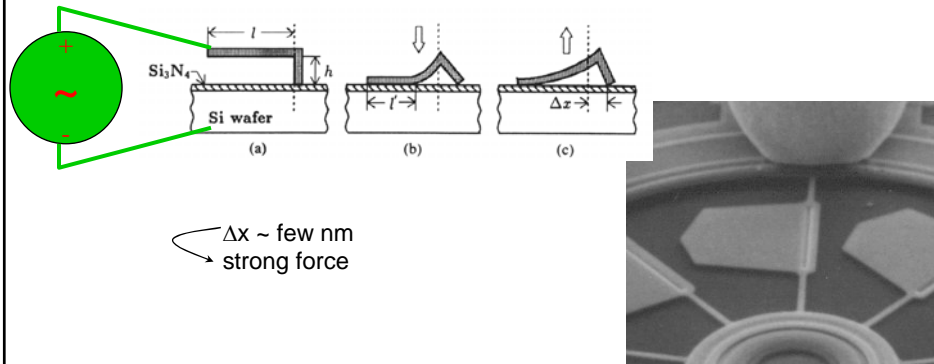


## Actuators: Electrostatic

- Comb Drive Notes:
  - Displacement vs. Actuation Voltage
  - Spring Constants

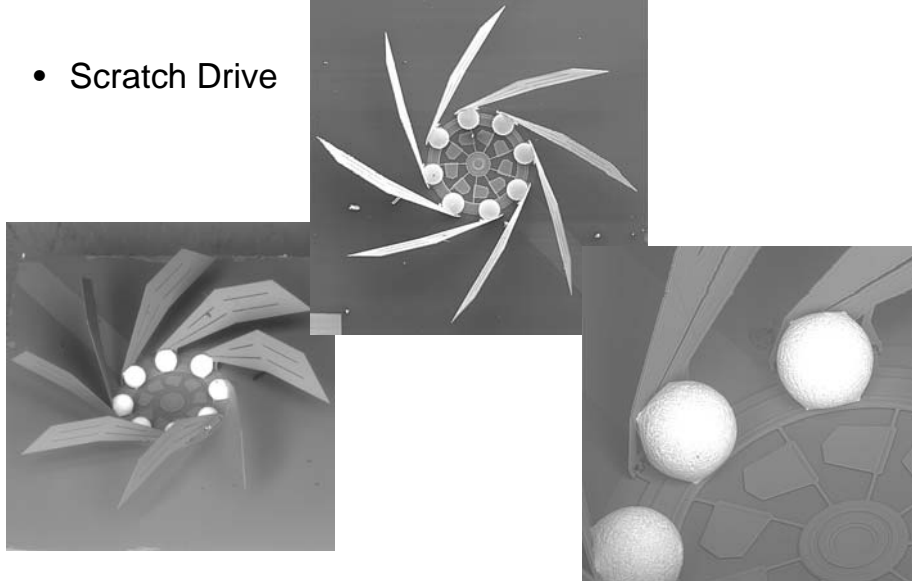
## Actuators: Electrostatic

- Scratch Drive
  - First demonstrated by:
    - T Akiyama and K. Shono, "Controlled Stepwise Motion in Polysilicon Microstructures, Journal of Microelectromechanical Systems, vol. 2, pp. 106-110, Sept 1993.



## Actuators: Electrostatic

- Scratch Drive



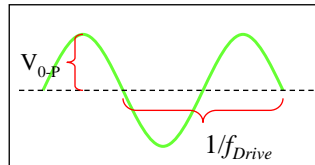
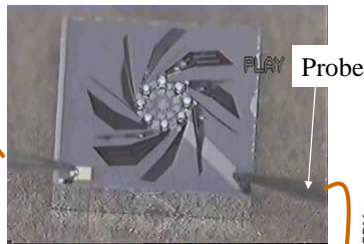
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25

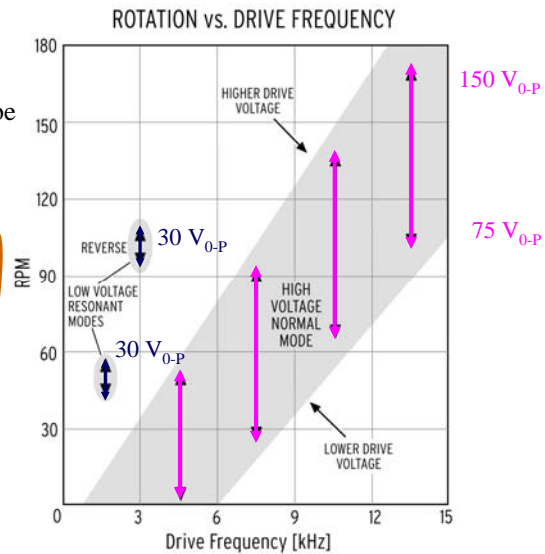
## Actuators: Electrostatic

- Scratch Drive



Function Generator & Amplifier

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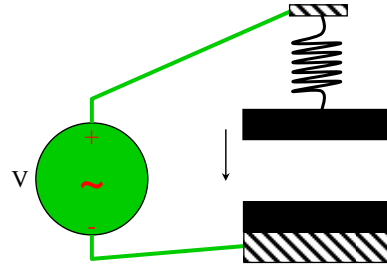
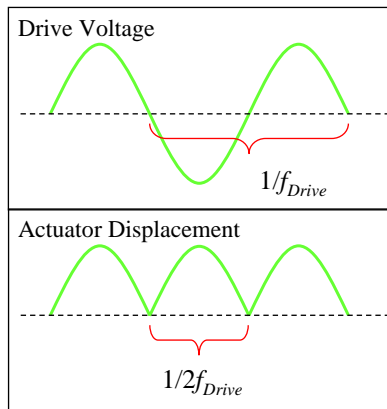


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26

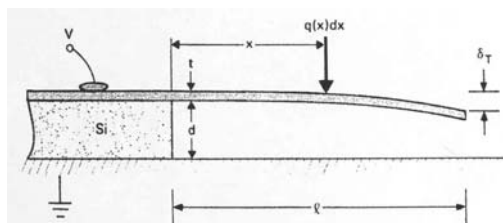
## Actuators: Electrostatic

- When driving with a zero-bias input signal, the frequency of operation is twice the input signal frequency!

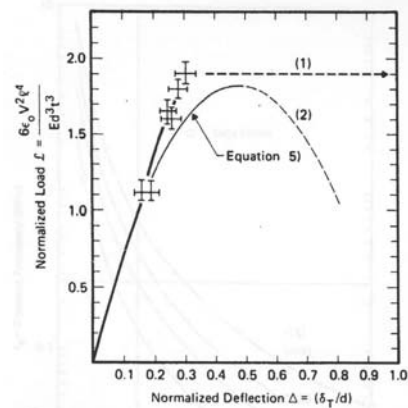


## Actuators: Electrostatic

- Cantilever
  - Simpler Structure
  - Modeling Voltage vs. Deflection more complicated.

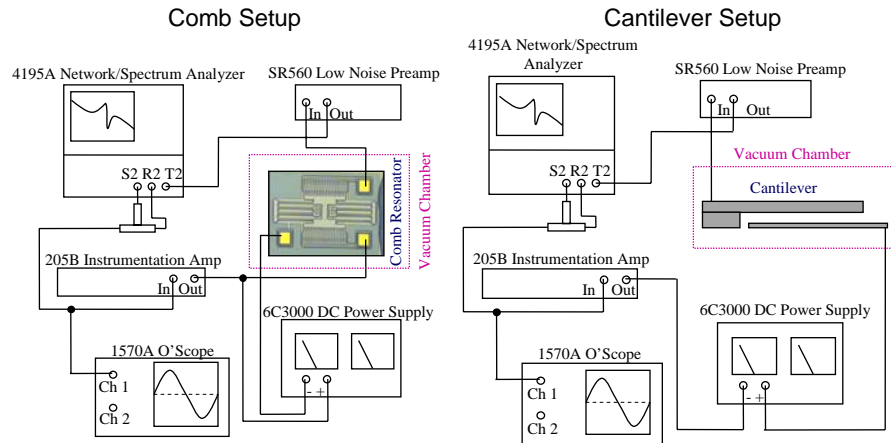


K. E. Petersen, "Dynamic Micromechanics on Silicon: Techniques and Devices," *IEEE Transactions on Electron Devices*, vol. ED-25, no. 10, 1978.



# Actuators: Resonant Frequency

- Best and Easiest: By Eye 
- 2nd Best: Electrically (Network/Spectrum Analyzer/Impedance Analyzer)



W. D. Cowan, V. M. Bright, and G. C. Dalton, "Measuring Frequency Response of Surface-Micromachined Resonators," *The Proceedings of SPIE*, vol. 3225, pp. 32-43, 1997. Figures formatted by Victor Bright.  
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# Actuators

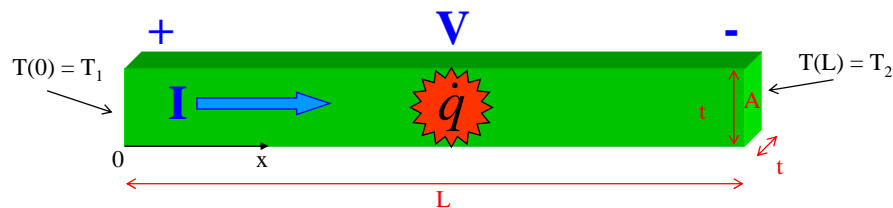
- Transducers
- Actuators
  - Electrostatic
  - **Electro-Thermal**
  - Bimorph Electro-Thermal
  - Residual Stress
  - Mechanical Components

## Actuators: Electro-Thermal

- Advantages
  - Simple Designs
  - Simple Fabrication
  - High Force Per Unit Volume
  - Low Voltage
- Disadvantages
  - Temperature Dependent
  - High Electric Power Consumption
  - Low Frequency Operation

## Actuators: Electro-Thermal

- Material expands due to Ohmic or Joule Heating causing motion of actuator structure.



$$q = \text{Power} = I^2 R = \frac{I^2 L \rho}{A} \text{ or } \frac{V^2}{R} = \frac{V^2 A}{L \rho} \quad \dot{q} = \frac{\text{Power}}{\text{Volume}} = \frac{I^2 \rho}{A^2} \text{ or } \frac{V^2}{L^2 \rho}$$

Heat Transfer

$$k \frac{\partial^2 T}{\partial x^2} + \dot{q} = 0$$

$$T(x) = \frac{1}{2k} \dot{q} (Lx - x^2) + \frac{1}{L} (T_2 - T_1)x + T_1$$

Thermal Expansion

$$L_{\text{new}}(x) = \int_0^x [1 + \alpha(T(\chi) - T_0)] d\chi$$

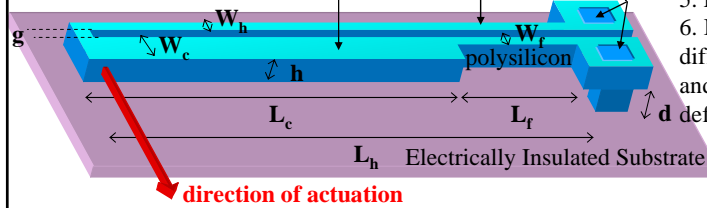
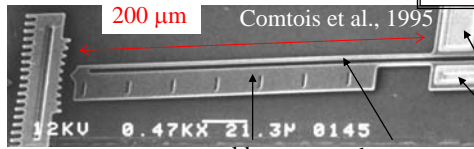


# Actuators: Electro-Thermal

- Laterally/Horizontally Deflecting
  - Motion that is parallel to the plane of the substrate

### Example properties needed for modeling an electro-thermal actuator:

$\rho$  = electrical resistivity =  $2.3 \times 10^{-5} \Omega\text{m}$   
 $\alpha$  = coefficient of thermal expansion =  $29 \times 10^{-7} \text{K}^{-1}$   
 $\alpha_r$  = temperature coefficient of resistance =  $1.25 \times 10^{-3} \text{K}^{-1}$   
 $k$  = thermal conductivity =  $32 \text{W/mK}$   
 $E$  = Young's modulus =  $169 \text{GPa}$   
 $\nu$  = Poisson's ratio =  $0.22$



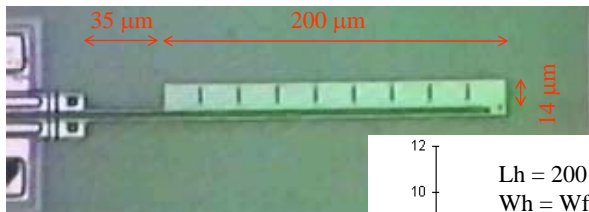
### Optimum Dimensions:

1.  $g$  = as small as possible
2.  $h$  = as tall as possible
3.  $W_c/W_h = 7$
4.  $W_h$  = as small as possible
5.  $L_f \approx L_h/4$
6. Increasing the temp. difference between the cold and hot arm increases deflection.

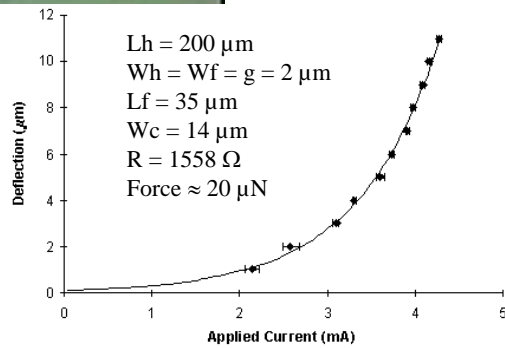


# Actuators: Electro-Thermal

- Laterally (Horizontally) Deflecting



V. Bright et al., AFIT, 1996



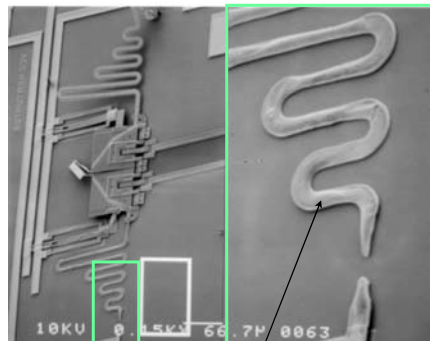
Comtois et al., 1995

# Actuators: Electro-Thermal

- Low resistance wiring and Si/Au eutectic



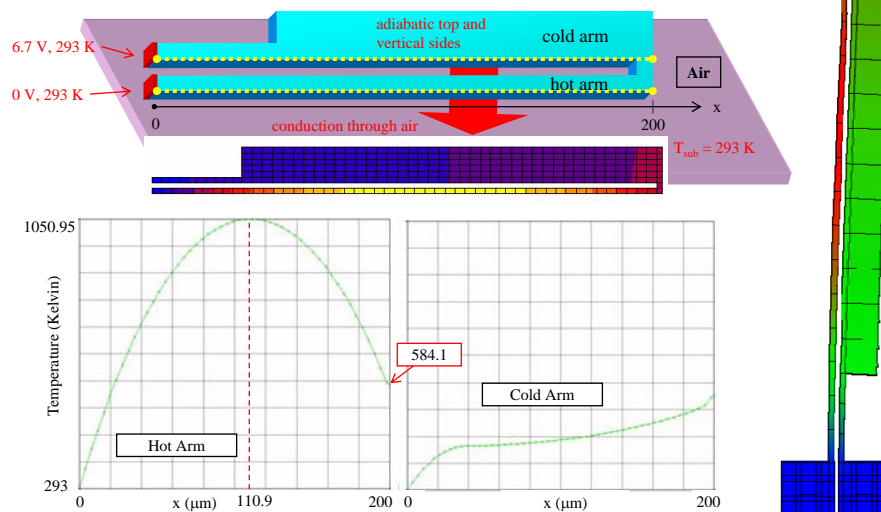
“Burned out” electro-thermal actuator hot arm



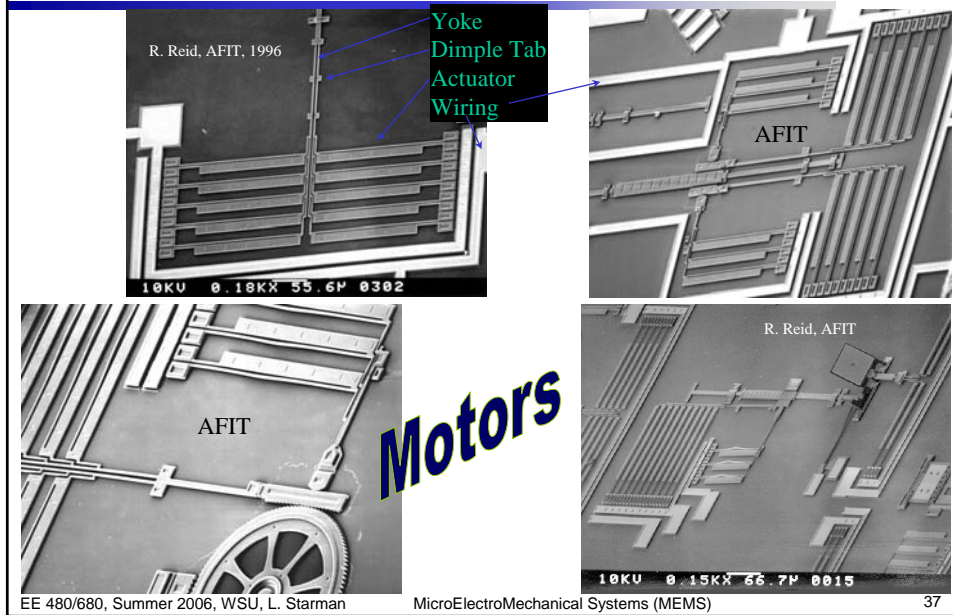
Eutectic Compound 18.6%Si/81.4%Au with melting temperature of 363 °C

# Actuators: Electro-Thermal

- Temperature Distribution (Relative Magnitude)



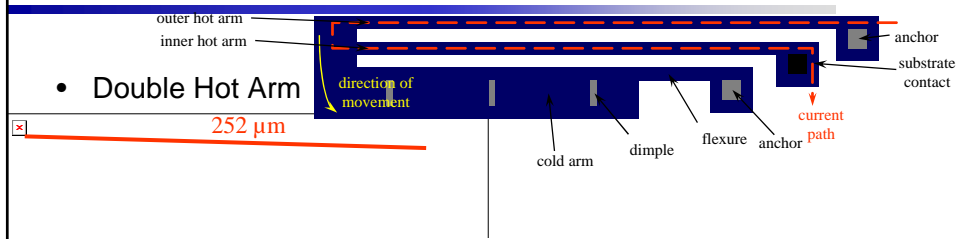
## Actuators: Electro-Thermal



## Actuators: Electro-Thermal



# Actuators: Electro-Thermal



- Double Hot Arm

D. Burns et al., AFIT

Design measurements for thermal actuators

	1-H actuator	2-H actuator
Electrical resistance	1.510 KΩ	2.413 KΩ
Maximum deflection (positive)	10 μm	14 μm
Maximum deflection (backbending)	8 μm	12 μm
Maximum force	11.4 μN	20.5 μN
Maximum current before backbending (under load)	5.12 mA	5.59 mA
Maximum operating frequency (air)	12 KHz	17 KHz
Maximum operating frequency (40 mTorr)	4 KHz	27 KHz

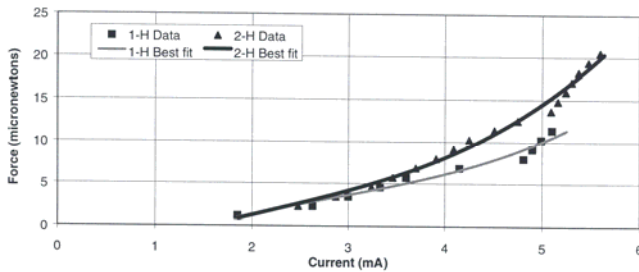
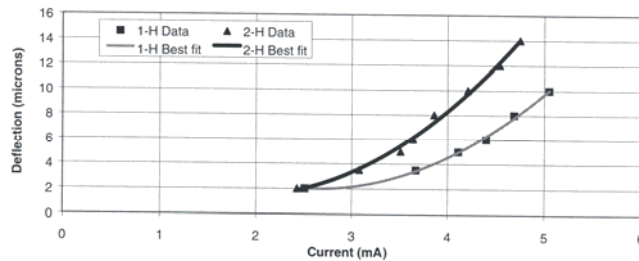
	1-H actuator	2-H actuator
Cold arm length	162 μm	162 μm
Cold arm width	14 μm	14 μm
Flexure length	38 μm	38 μm
Flexure width	2.5 μm	2.0 μm
Inner hot arm length	200 μm	221 μm
Outer hot arm length	not applicable	252 μm
Hot arm width	2.5 μm	2.5 μm
Separation between inner hot arm and cold arm	3 μm	3 μm
Separation between hot arms	not applicable	3 μm

Comparison of single hot-arm (1-H) and double hot-arm (2-H) actuator operating properties

# Actuators: Electro-Thermal

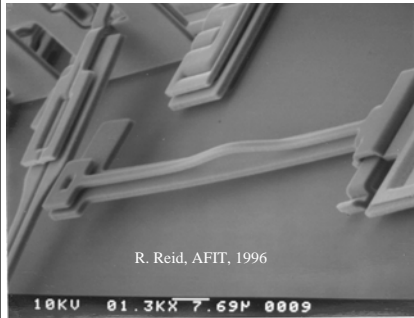
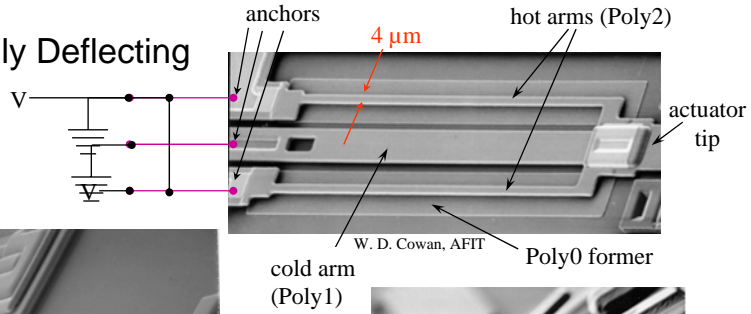
- Double Hot Arm

D. Burns et al., AFIT



# Actuators: Electro-Thermal

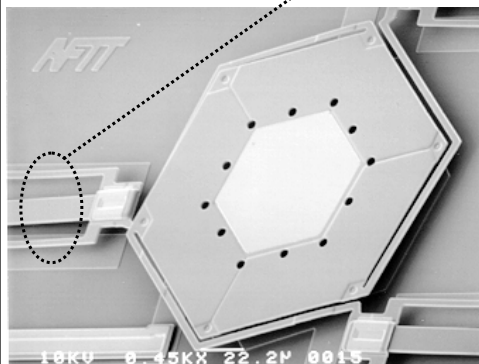
- Vertically Deflecting



# Actuators: Electro-Thermal

- Piston Mirrors

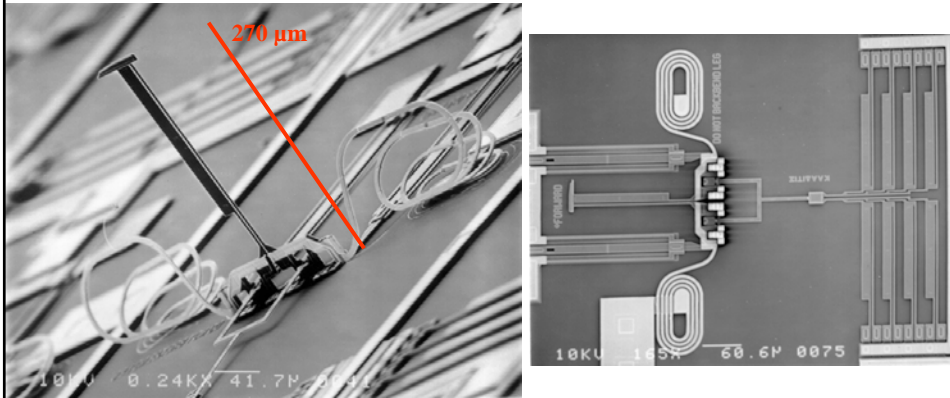
An actuator



W. D. Cowan, AFIT

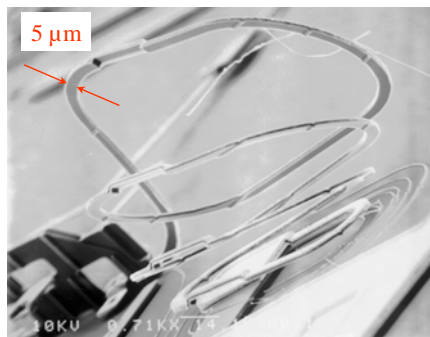
## Actuators: Electro-Thermal

- Assembled Devices: Micro-Robot Leg

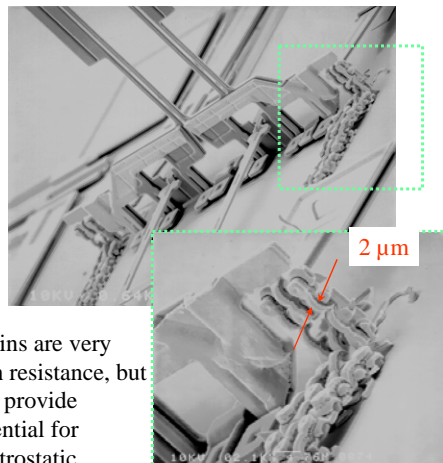


## Actuators: Electro-Thermal

- Low resistance wire necessary for electro-thermal actuation



Spring wire is a good low resistance electrical path

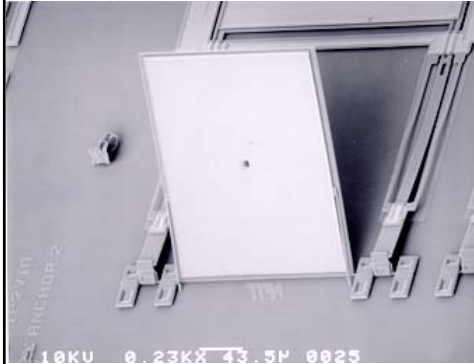


Chains are very high resistance, but will provide potential for electrostatic actuators

*Does not work for electro-thermal*

## Actuators: Electro-Thermal

- Assembled Devices: Mirror & Micro-Grippers



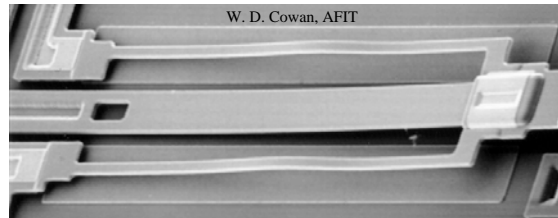
W. D. Cowan, AFIT



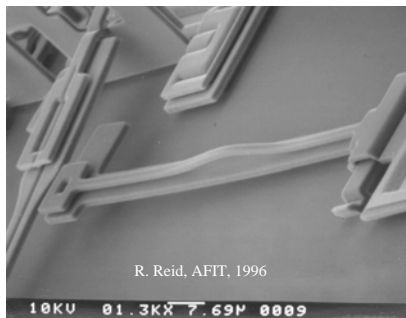
J. Comtois, AFIT

## Actuators: Electro-Thermal

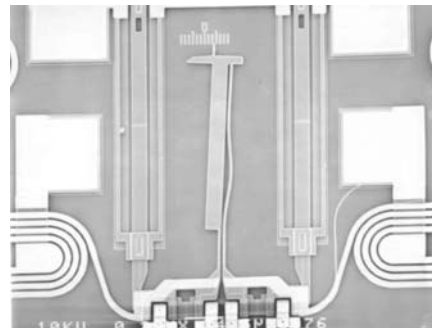
- Back bending
  - The permanent plastic deformation of a "hot arm".
  - Performed once before beginning normal operation.



W. D. Cowan, AFIT

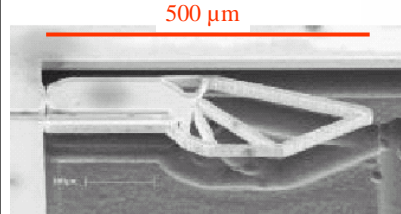
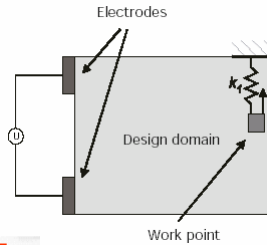


R. Reid, AFIT, 1996



# Actuators: Electro-Thermal

- The design of an electro-thermal actuator is a compromise between thermal and mechanical efficiency!
- Optimized design by J. Jonsmann et al., "Compliant Electro-thermal Microactuators," 1999.
  - Design domain size
  - Location of electrodes
  - Location of work point
  - Electrical resistance
  - Amount of material used
  - Available voltage

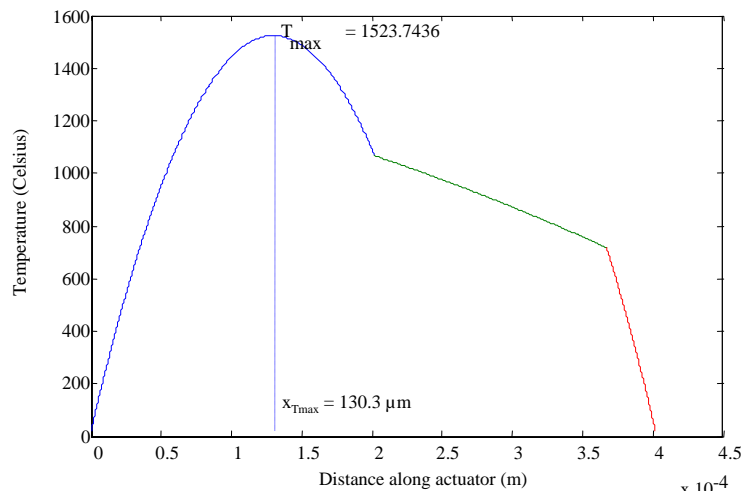


- 1 μm e-Si on 2.1 μm SiO<sub>2</sub>
- Laser micro machining
- Anisotropic SiO<sub>2</sub> RIE
- Anisotropic Si RIE
- Thermal oxidation
- 100 Å Ti, 1000 Å Au evaporated
- Electroplating of Ni
- Gold etched
- SiO<sub>2</sub> etched
- Structure underetched

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# Actuators: Electro-Thermal

- Optional:
  - Analytical modeling of the temperature distribution of a laterally deflecting electro-thermal actuator.



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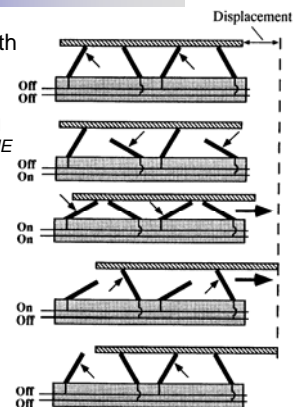
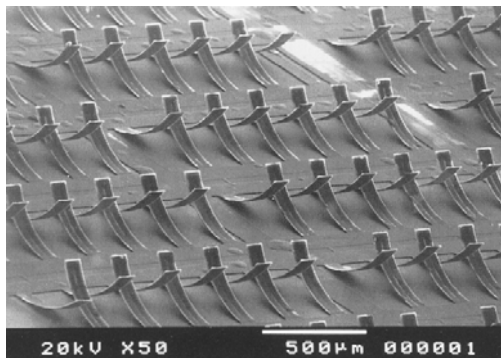


## Overview

- Transducers
- Actuators
  - Electrostatic
  - Electro-Thermal
  - Bimorph Electro-Thermal
  - Residual Stress
  - Mechanical Components

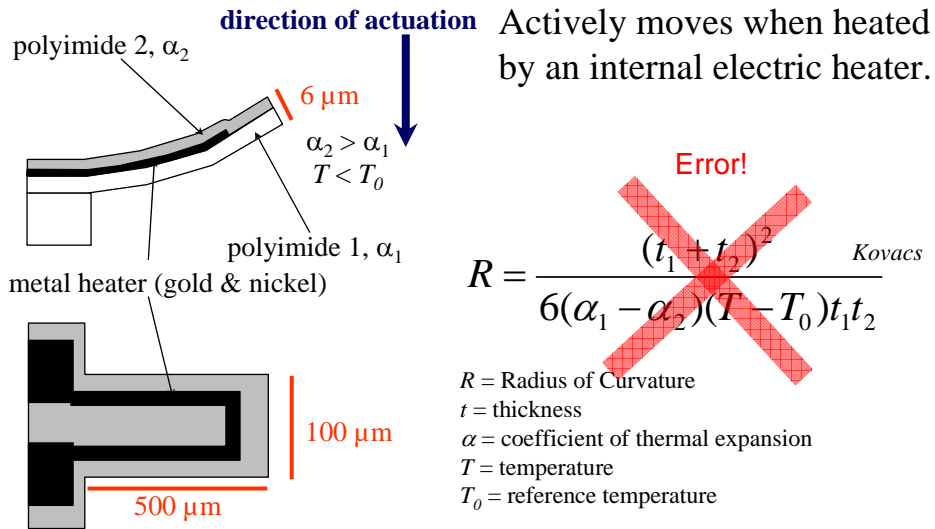
## Actuators: Bimorph Electro-Thermal

- An actuator made up of a sandwich of at least two layers with different coefficients of thermal expansion and an internal electric heater.
  - Ex. M. Ataka, S. Omofsk, N. Takeshima, and H. Fujita, "Fabrication and operation of polyimide bimorph actuators for a ciliary motion," *IEEE/ASME Journal of Microelectromechanical Systems*, vol. 2, no. 4, pp. 146-150, Dec. 1993.



Vanderbilt

## Actuators: Bimorph Electro-Thermal

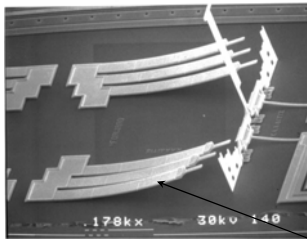


## Overview

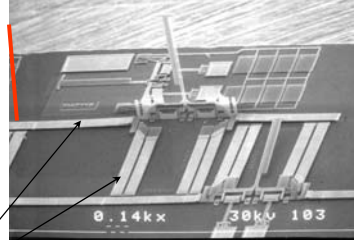
- Transducers
- Actuators
  - Electrostatic
  - Electro-Thermal
  - Bimorph Electro-Thermal
  - Residual Stress
  - Mechanical Components

## Actuators: Residual Stress

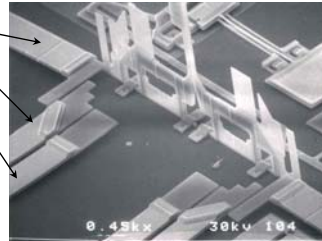
- A passive actuator, usually in the form of a cantilever, made up of a sandwich of at least two layers with different coefficients of thermal expansion.



270  $\mu\text{m}$



stressed cantilevers

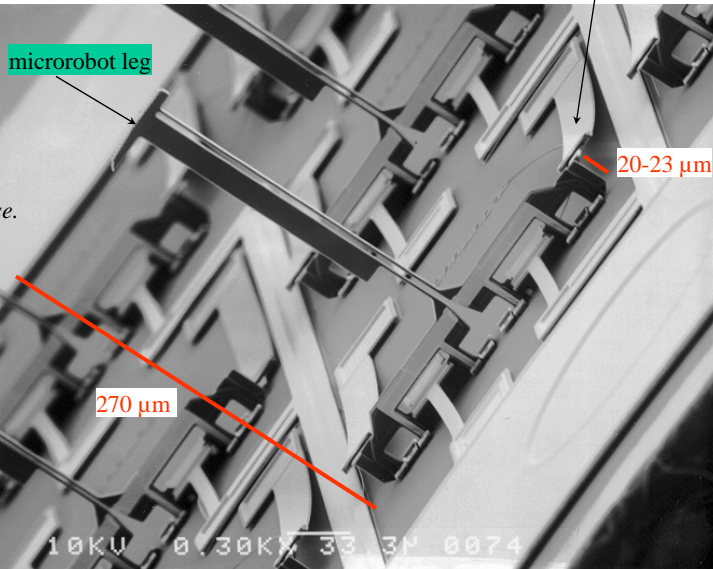


*Assembled with residual stress cantilevers.*

*Possibly assisted by unintentional agitation during release, rinse, and/or dry.*

## Actuators: Residual Stress

stressed cantilever



microrobot leg

*Assembled with intentional agitation during release and rinse.*

*Assisted by stressed cantilevers.*

20-23  $\mu\text{m}$

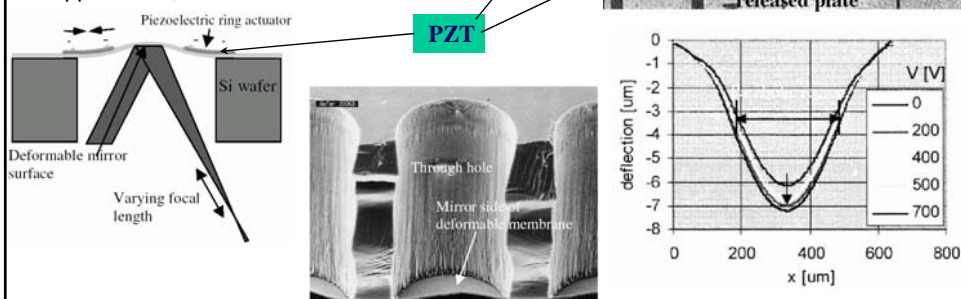
270  $\mu\text{m}$

## Actuators: Other

- Most other actuators are further extensions of the basic examples covered in the previous slides.
- Other types of actuation include:
  - Piezoelectric
  - Magnetic / Electro-Magnetic
  - Pneumatic
  - Shape Memory Alloy

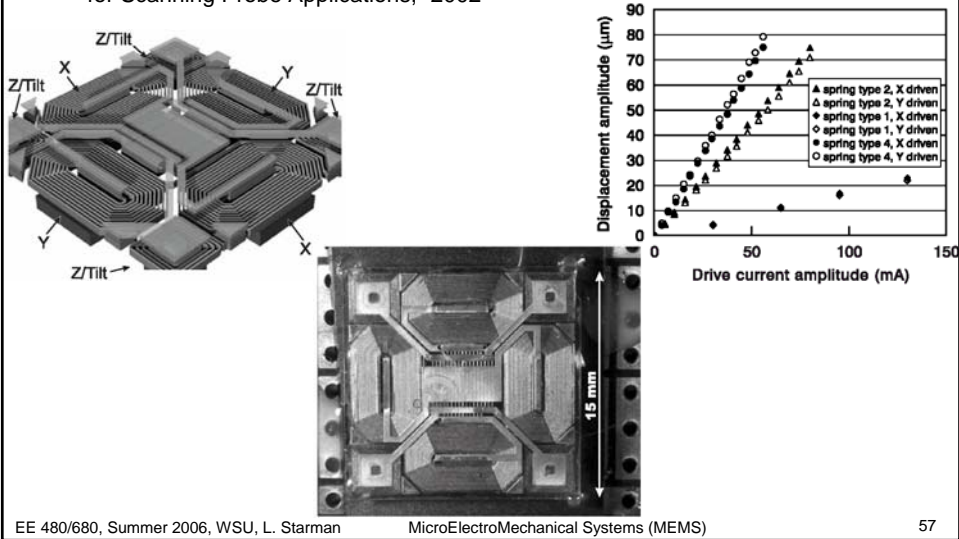
## Actuators: Piezoelectric

- In a piezoelectric material, an applied voltage induces an internal stress, resulting in an expansion of the material.
- Conversely, for sensor use, the application of an external force induces an electric field across the material.
- Ex. M. J. Mescher et al., "A Novel High-speed Piezoelectric Deformable Varifocal Mirror For Optical Applications," 2002.



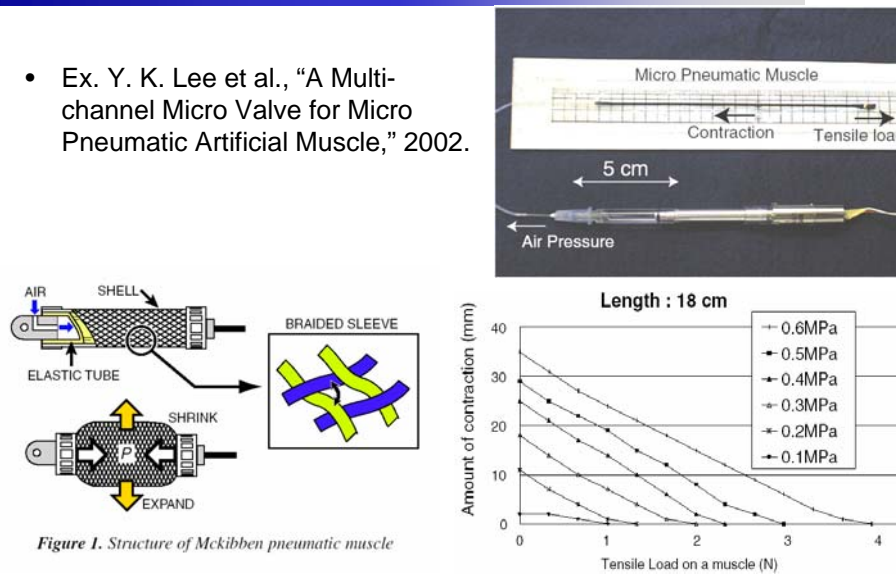
## Actuators: Magnetic / Electro-Magnetic

- Ex. H. Rothuizen et al., "Compact Copper/epoxy-based Electromagnetic Scanner for Scanning Probe Applications," 2002



## Actuators: Pneumatic

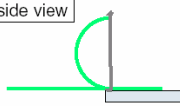
- Ex. Y. K. Lee et al., "A Multi-channel Micro Valve for Micro Pneumatic Artificial Muscle," 2002.



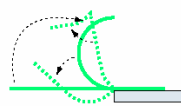
## Actuators: Shape Memory Alloy (SMA)

- Ex.: S. Takeuchi, "Three Dimensional SMA Microelectrodes with Clipping Structure for Insect Neural Recording," 1999.

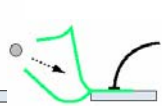
side view



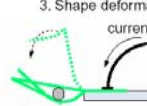
1. Remove the Al wire



2. Deform the shape



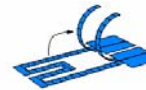
1. Insert the nerve



2. Clip the nerve by supply current for Joule heating



1. Patterning



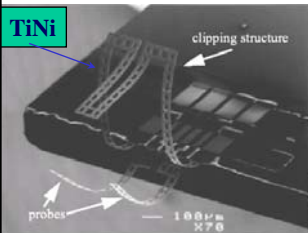
2. 3D shape memorization



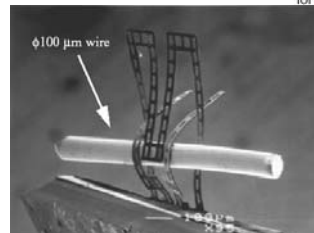
3. Shape deformation



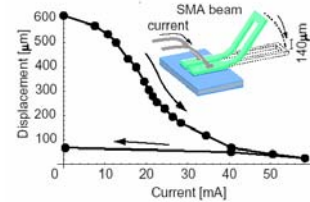
4. Heating up the structure



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59

## Overview

- Transducers
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60

### Mechanical Components: Substrate or Staple Hinges

Anchor2

Poly2

Poly1

$3 \mu\text{m}$

$$l_{h1} \geq \frac{t_{p1} \cos(\alpha) + t_{p2}}{\sin(\alpha)}$$

$$l_{h2} \geq \frac{t_{p1} + t_{p2} \cos(\alpha)}{\sin(\alpha)}$$

$l_{h1} + l_{h2} \geq \text{minimum fabrication spacing (for } \alpha > 90^\circ \text{)}$

Structure 2  $t_{p2}$

Structure 1  $t_{p1}$

Substrate

$l_{h1}$

Solder

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### Mechanical Components: Scissor Hinges

- “Up - Folding”  $l_h \geq t_p \cot\left(\frac{\alpha}{2}\right)$
- $l_h \geq \text{minimum fabrication spacing (for } \alpha > 90^\circ \text{)}$

Substrate Side

Structure 1

Substrate Side

$t_p$

$l_h$

$\alpha$

Poly 2

Poly 1

minimum spacing

$l_h$

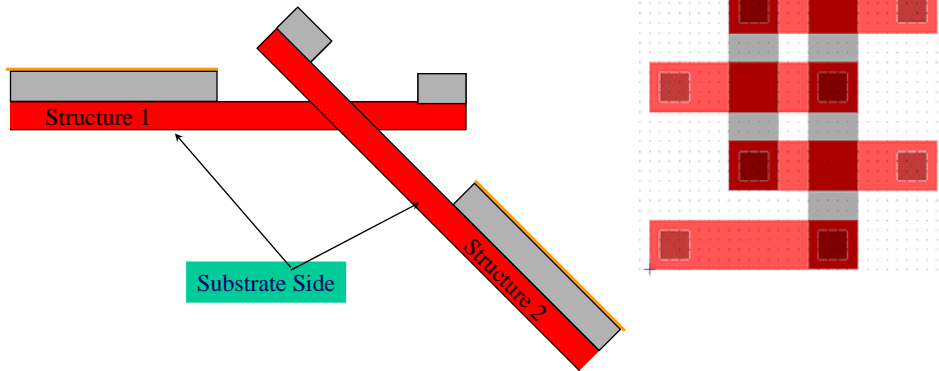
Solder

$l_h$

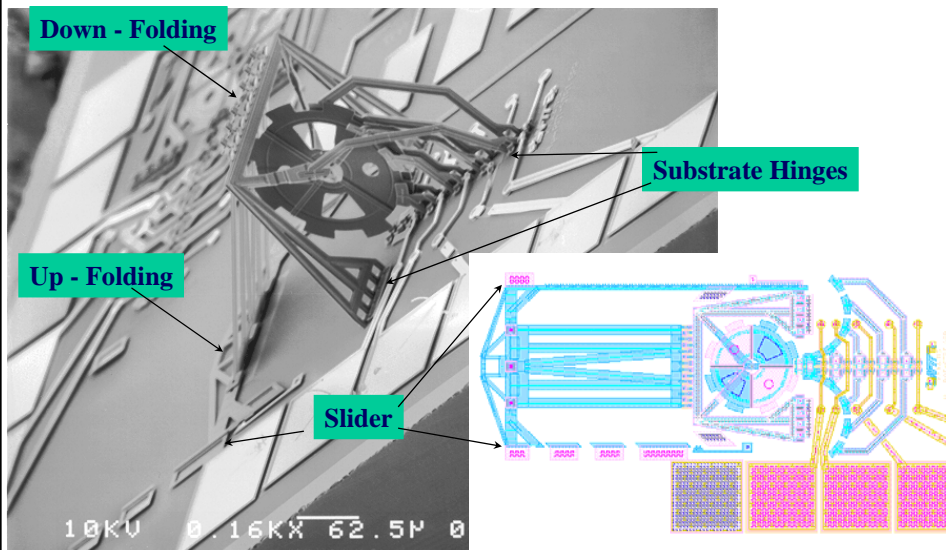
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## Mechanical Components: Scissor Hinges

- “Down - Folding”

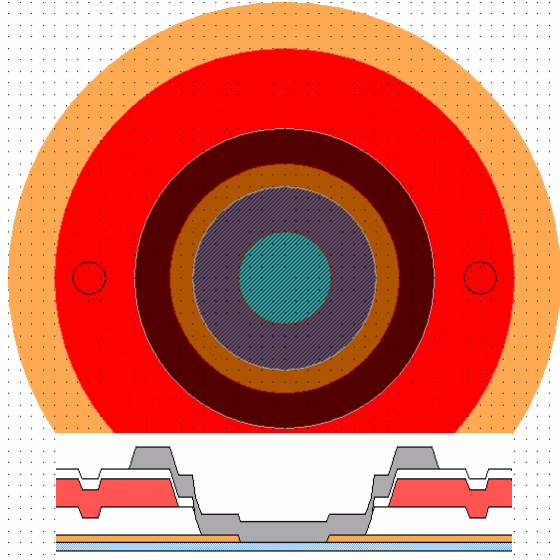
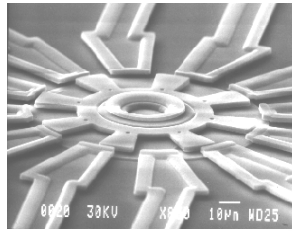


## Mechanical Components: Hinges





## Mechanical Components: Pin Joint

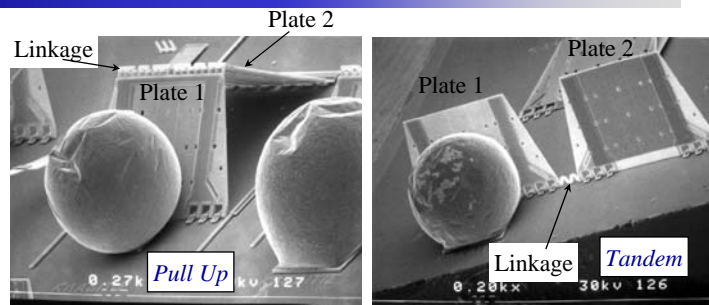


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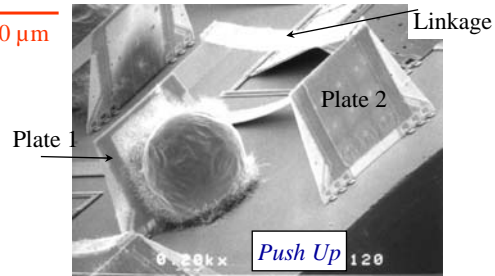
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65

## Mechanical Components: Linkages



200 µm

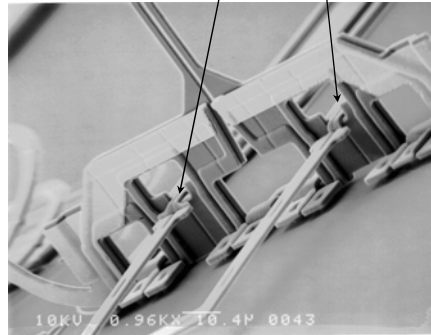


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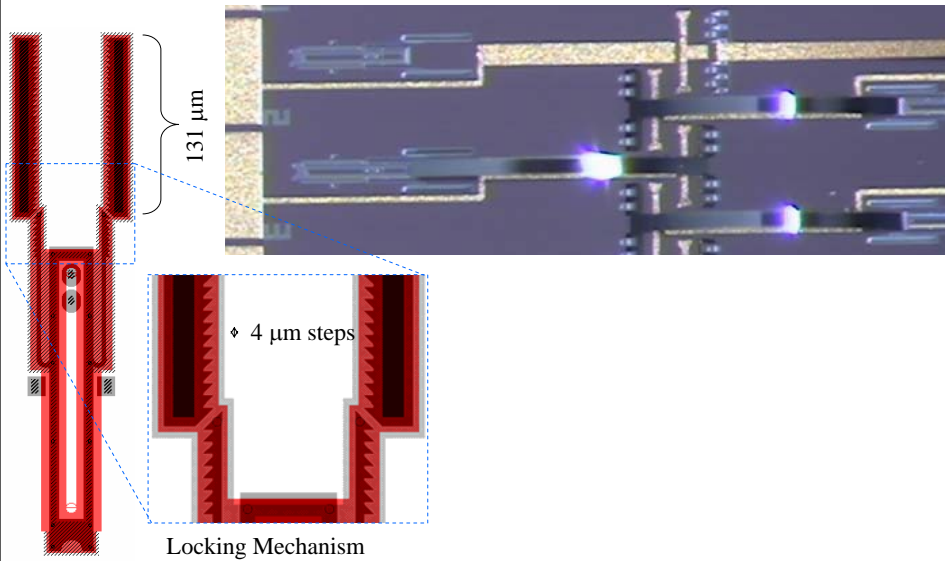
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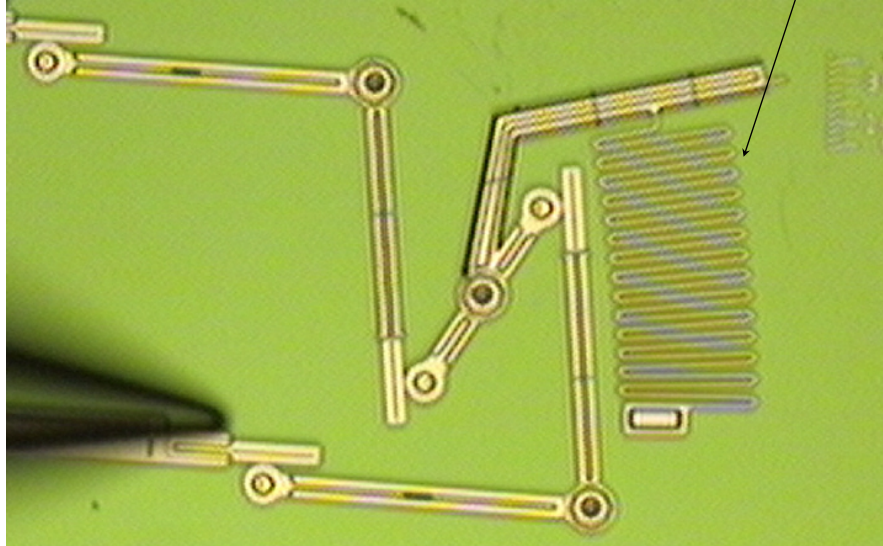
## Mechanical Components: Locks



## Mechanical Components: Locks



## Mechanical Components: Springs



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## Mechanical Components: Other

- Gears
- Flexible Hinges
- Corrugation or Stiffening

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70